ABSTRACT

SYSTEM FOR SEMICONDUCTOR PACKAGE WITH STACKED DIES

A semiconductor package with stacked dies and method of assembly is provided. A first die is attached to a substrate. A protective layer is placed on the first die over a central area thereof. The first die is electrically connected to the substrate. An intermediate adhesive layer is applied over the protective layer. A second die is attached to the intermediate adhesive layer and electrically connected to the substrate. (Fig. 9)